

Motion SPM[®] 5 Series FSB50550BB

General Description



ORDERING INFORMATION

Device	Device Marking	Package	Packing Type	Quantity
FSB50550BB	FSB50550BB	SPM5T–021 (Pb–Free)	Rail	15

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Rating	Unit
INVERTER PA	RT (Each MOSFET Unless Otherwise Specifie	d)		
V _{DSS}	Drain-Source Voltage of Each MOSFET		500	V
*I _{D 25}	Each MOSFET Drain Current, Continuous	$T_{\rm C} = 25^{\circ}{\rm C}$	3.0	А
*I _{D 80}	Each MOSFET Drain Current, Continuous	$T_{C} = 80^{\circ}C$	1.9	А
*I _{DP}	Each MOSFET Drain Current, Peak	T _C = 25°C, PW < 100 μs	7.0	А
*I _{DRMS}	Each FRFET Drain Current, Rms	$T_C = 80^{\circ}C, F_{PWM} < 20 \text{ kHz}$	1.3	A _{rms}
CONTROL PA	RT (Each HVIC Unless Otherwise Specified)			
V _{DD}	Control Supply Voltage	Applied Between V _{DD} and COM	20	V
V _{BS}	High-side Bias Voltage	Applied Between V_{B} and V_{S}	20	V
V _{IN}	Input Signal Voltage	Applied Between IN and COM	-0.3~V _{DD} + 0.3	V
BOOTSTRAP	DIODE PART (Each Bootstrap Diode Unless O	therwise Specified.)		
V _{RRMB}	Maximum Repetitive Reverse Voltage		500	V
* I _{FB}	Forward Current	$T_{\rm C} = 25^{\circ}{\rm C}$	0.5	А
* I _{FPB}	Forward Current (Peak)	T_{C} = 25°C, Under 1 ms Pulse Width	2.0	А
THERMAL RE	SISTANCE			
R _{th(j-c)Q}	Junction to Case Thermal Resistance (Note 1)	Each FET under inverter operating condition (Note 1)	8.9	°C/W
TOTAL SYSTE	M	-		
TJ	Operating Junction Temperature		-40~150	°C
T _{STG}	Storage Temperature		-40~125	°C
V _{ISO}	Isolation Voltage	60 Hz, Sinusoidal, 1 minute, Connect Pins to Heat Sink Plate		

PIN DESCRIPTIONS

Pin No.	Pin Name	Pin Description
1	СОМ	IC Common Supply Ground
2	V _{B(U)}	Bias Voltage for U–Phase High–Side MOSFET Driving
3	V _{DD(U)}	Bias Voltage for U–Phase IC and Low–Side MOSFET Driving
4	IN _(UH)	Signal Input for U-Phase High-Side
5	IN _(UL)	Signal Input for U-Phase Low-Side
6	N.C	No Connection
7	V _{B(V)}	Bias Voltage for V–Phase High Side MOSFET Driving
8	V _{DD(V)}	Bias Voltage for V–Phase IC and Low Side MOSFET Driving
9	IN _(VH)	Signal Input for V–Phase High–Side
10	IN _(VL)	Signal Input for V–Phase Low–Side
11	N.C	No Connection
12	V _{B(W)}	Bias Voltage for W–Phase High–Side MOSFET Driving
13	V _{DD(W)}	Bias Voltage for W–Phase IC and Low–Side MOSFET Driving
14	IN _(WH)	Signal Input for W–Phase High–Side
15	IN _(WL)	Signal Input for W–Phase Low–Side
16	V _{TS}	Output for HVIC Temperature Sensing
17	Р	Positive DC-Link Input
18	U, V _{S(U)}	Output for U–Phase & Bias Voltage Ground for High–Side MOSFET Driving
19	NU	Negative DC-Link Input for U-Phase
20	N _V	Negative DC-Link Input for V-Phase
21	V, V _{S(V)}	Output for V–Phase & Bias Voltage Ground for High–Side MOSFET Driving
22	N _W	Negative DC-Link Input for W-Phase
23	W, V _{S(W)}	Output for W Phase & Bias Voltage Ground for High–Side MOSFET Driving

Figure 1. Pin Configuration and Internal Block Diagram (Bottom View)

ELECTRICAL CHARACTERISTICS (T_J = 25°C, V_{DD} = V_{BS} = 15 V Unless Otherwise Specified.)

Symbol	Parameter	Test Conditions		Тур.	Max.	Unit	
INVERTER	INVERTER PART (Each MOSFET Unless Otherwise Specified)						
BV _{DSS}	Drain – Source Breakdown Voltage	V _{IN} = 0 V, I _D = 1 mA (Note 4)	500	-	-	V	
I _{DSS}	Zero Gate Voltage Drain Current	V _{IN} = 0 V, V _{DS} = 500 V	-	-	1	mA	
R _{DS(on)}	Static Drain – Source Turn–On Resistance	$V_{DD} = V_{BS} = 15 \text{ V}, V_{IN} = 5 \text{ V}, I_D = 1.2 \text{ A}$	-	2.3	3.0	Ω	
V_{SD}	Drain – Source Diode Forward Voltage	$V_{DD} = V_{BS} = 15$ V, $V_{IN} = 0$ V, $I_D = -1.2$ A	1	1	1.3	V	
t _{ON}	Switching Times	$V_{PN} = 300 \text{ V}, V_{DD} = V_{BS} = 15 \text{ V}, I_D = 1.2 \text{ A}$		780	1100	ns	
t _{OFF}		High- and Low-Side MOSFET Switching (Note 5)	1001	1660	2300	ns	
t _{rr}			-	230	-	ns	

RECOMMENDED OPERATING CONDITION

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
V _{PN}	Supply Voltage	Applied between P and N	-	300	400	V
V _{DD}	Control Supply Voltage	Applied between V_{DD} and COM	13.5	15.0	18.5	V
V _{BS}	High-Side Bias Voltage	Applied between V_{B} and V_{S}	13.5	15.0	18.5	V
V _{IN(ON)}	Input ON Threshold Voltage	Applied between V_{IN} and COM	3.0	-	V_{DD}	V
V _{IN(OFF)}	Input OFF Threshold Voltage		0	-	0.6	V
t _{dead}	Blanking Time for Preventing Arm–Short	$V_{DD} = V_{BS} = 13.5 16.5 \text{ V}, \text{ T}_{J} \le 150^{\circ}\text{C}$	2	-	-	μs
		V_{DD} = V_{BS} = 12.3~14.4 V, T_J \leq 150°C	1	-	-	μs
f _{PWM}	PWM Switching Frequency	T _J ≤ 150°C	_	15	_	kHz

Functional









SPM5T-021 / 21LD, PDD STD, FULL PACK, DOUBLE DIP TYPE CASE MODET ISSUE O

DATE 31 JAN 2017

NOTES: UNLESS OTHERWISE SPECIFIED

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